
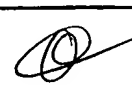
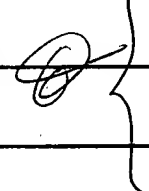



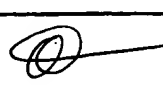
<b>INFORMATION DISCLOSURE</b> <b>CITATION IN AN</b> <b>APPLICATION</b>				ATTY. DOCKET NO. <b>49657-217</b>		SERIAL NO.	
(PTO-1449)				APPLICANT <b>Shigeki OHBAYASHI</b>			
				FILING DATE <b>November 20, 1998</b>		GROUP <b>2133</b>	



U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,703,510	Dec. 30, 1997	Iketani et al. — Duplicate			

FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	06-069425	March 11, 1994	Japan (with English abstract)	Duplicate			
	06-005069	Jan. 14, 1994	Japan (with English abstract)				
	02-302987	Dec. 14, 1990	Japan (with English abstract)				

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	
	JEDEC Standard No. 21-C, JEDEC, December 22, 1994, pp. 3.7.8-7 — Duplicate
	"BGA Packages, Gaining Popularity in U.S.; Make High Density Mounting of High Pin Count LSIs Easy", A. Fukuda, Nikkei Electronics, Feb. 14, 1994, pp. 59-73.
	M5M5V1132FP, GP-6, -7, -8, -7L, -8L, Mitsubishi's Product Data Sheet March 24, 1997, pp. 1-14. — Duplicate

EXAMINER 	DATE CONSIDERED <b>8/16/05</b>
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.